

OCT 25 2005

Patent

Docket No. MTI-31607

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Lee, Teck et al.
 Serial No. : 10/050,507
 Filing Date : January 16, 2002
 For : Elimination of RDL Using Tape Base Flip Chip on Flex for
 Die Stacking
 Examiner : THOMPSON, Craig
 Confirmation No. : 7687
 Group Art Unit : 2813

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

I hereby certify that, on the date shown below, this correspondence is being transmitted to Fax No. 571-273-8300 addressed to Examiner THOMPSON at the US Patent and Trademark Office.

Date: _____

Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

STATUS INQUIRY

Dear Sir:

This application was filed on January 16, 2002, and the last correspondence filed in this application is a Request for Continued Examination (RCE) submitted May 10, 2005.

More than fifty-seven (57) months (from the filing date), and five (5) months (from the mailing date of the RCE) have passed without receiving any communication from the U.S. Patent and Trademark Office. Please provide us with a status of this application.

Respectfully submitted,

Dated: October 25, 2005

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